ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION # 16790CA

Generic Copy

Issue Date: 23-Jul-2012

TITLE: Final PCN for wafer fab transfer from Gunma to the On Semiconductor wafer fab ISMF in Malaysia.(Group CA).

PROPOSED FIRST SHIP DATE: starting on 15 Oct 2012 until 30 Oct 2012 (the actual ship date will be different by each product, please check the responsible Sales person).

AFFECTED CHANGE CATEGORY(S): Wafer Fabrication Location Change

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Toshikazu.Hirai@onsemi.com

SAMPLES: Contact your local ON Semiconductor Sales Office or Akira.Yoneyama@onsemi.com

ADDITIONAL RELIABILITY DATA: May be available
Contact your local ON Semiconductor Sales Office or Yasuhiro.Igarashi@onsemi.com.

NOTIFICATION TYPE:
Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>

DESCRIPTION AND PURPOSE:

This is a Final Process Change Notification to announce the transfer of products from Sanyo wafer fabrication sites located in Gifu to the ON Semiconductor wafer fabrication site in Seremban, Malaysia.

The product design and electrical specifications will remain identical. A full electrical characterization over the temperature range will be performed for each product to check the device functionality and electrical specifications. Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.

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QUALIFICATION PLAN:

Estimated Date for Qualification Completion: starting on January 2012 until March 2012, dependent of the process/product.
Samples should be available after completion of Qualification.

RELIABILITY DATA SUMMARY

Group CA

Test:	Conditions:	Interval:	Results
High Temperature Storage	Ta=150degC	1000 hrs	Pass
Temp Humidity Storage	Ta=85degC, RH=85%	1000 hrs	Pass
Steady State Operating Life	Tj=150degC	1000 hrs	Pass
High Temperature Reverse Bias	Ta=150degC,VCES=60V	1000 hrs	Pass
Temperature Cycle	Ta=-55degC to 150degC 30min each	200 cycles	Pass
Pressure Cooker	Ta=121degC,2.03×10^5Pa,100%	50 hrs	Pass
Solder Test	Ta=260degC,10s(Solder bath)	10 s	Pass

Notice) ※1 Pre-treatment: Resistance to Soldering heat (Flow:260degC/10s)

ELECTRICAL CHARACTERISTIC SUMMARY

There is no change in the electrical performance. Datasheet specifications remain unchanged.

PACKAGE CHANGE

As announced in FPCN16789, the package produced by SP Semiconductor, our external fab will be used due to flood damage to our Thailand factory (SSTH). For detailed package dimensions, please see each product catalog.

CHANGED PART IDENTIFICATION

To differentiate the manufacturing source, we are changing the product's bar-code label to identify each production factory as follows:

Current Part Number	NEW Part Number
2SC6082	2SC6082-1E

*Suffix-1E will be used to identify SP Semiconductor & Communication Co., Ltd

List of affected Generic parts:

Group FA

PART_ID（New PART ID）
2SC6082(2SC6082-1E)